

TD62387AFNG, TD62388AFNG

8CH LOW INPUT ACTIVE DARLINGTON SINK DRIVER

The TD62387AFNG and TD62388AFNG are non-inverting transistor arrays, which are comprised of eight NPN darlington output stages and PNP input stages.

All unites feature integral clamp diodes for switching inductive loads.

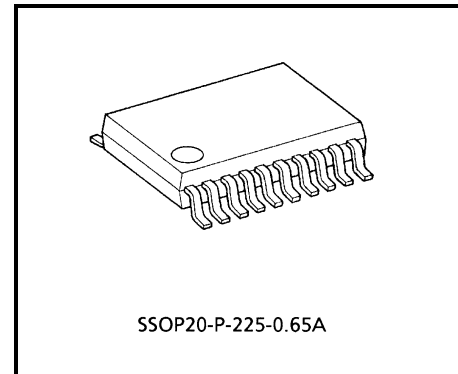
These devices are Low Level input active drivers and are suitable for operations with TTL, 5 V CMOS and 5 V Microprocessor which have sink current output drivers.

Applications include relay, hammer, lamp and LED driver.

This devices are a product for the Pb free(Sn-Ag).

FEATURES

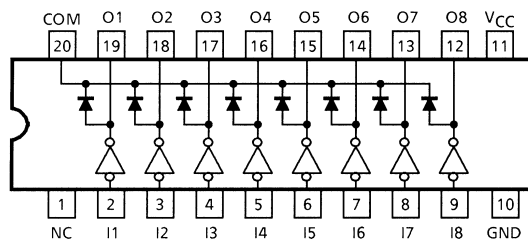
- Package Type : SSOP20 pin (0.65 mm pitch)
- High Sustaining Voltage : 50 V (Min)
- Output Current (Single Output) : 500 mA / ch (Max)
- Output Clamp Diodes
- Input : LOW LEVEL ACTIVE
- Standard Supply Voltage
- Inputs Compatible with TTL and 5 V CMOS



Weight: 0.09 g (Typ.)

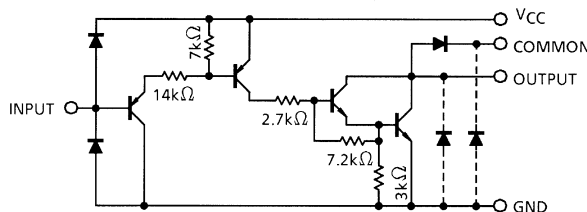
TYPE	$V_{IN(ON)}$
TD62387AFNG	0 V~ V_{CC} - 3.7 V
TD62388AFNG	

PIN CONNECTION (TOP VIEW)

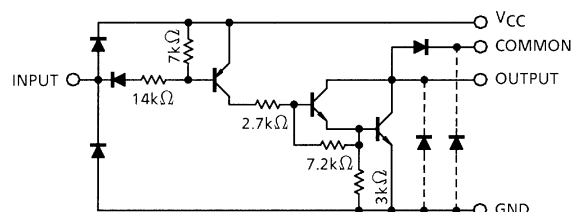


SCHEMATICS (EACH DRIVER)

TD62387AFNG



TD62388AFNG



Note: The input and output parasitic diodes cannot be used as clamp diodes.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Supply Voltage	V _{CC}	-0.5~7.0	V
Output Sustaining Voltage	V _{CE (SUS)}	-0.5~50	V
Output Current	I _{OUT}	500	mA / ch
Input Voltage	V _{IN}	-0.5~7.0	V
Input Current	I _{IN}	-10	mA
Clamp Diode Reverse Voltage	V _R	50	V
Clamp Diode Forward Current	I _F	500	mA
Power Dissipation	P _D	0.96 (Note)	W
Operating Temperature	T _{opr}	-40~85	°C
Storage Temperature	T _{stg}	-55~150	°C

Note: On Glass Epoxy PCB
(50 × 50 × 1.6 mm Cu 40%)

RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C)

CHARACTERISTIC	SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT
Supply Voltage	V _{CC}		4.5	5.0	5.5	V
Output Sustaining Voltage	V _{CE (SUS)}		0	—	50	V
Output Current	I _{OUT} (Note)	DC 1 Circuit	0	—	350	mA / ch
		T _{pw} = 25 ms 8 Circuits Ta = 85°C Tj = 120°C	Duty = 10%	0	—	180
			Duty = 50%	0	—	90
Input Voltage	V _{IN}		0	—	5.5	V
Clamp Diode Reverse Voltage	V _R		—	—	50	V
Clamp Diode Forward Current	I _F		—	—	400	mA
Power Dissipation	P _D		—	—	0.4	W

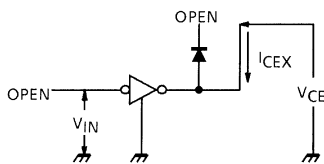
Note: On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 40%)

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

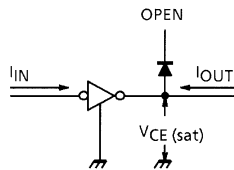
CHARACTERISTIC		SYMBOL	TEST CIR-CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Output Leakage Current		I_{CEX}	1	$V_{CC} = 5.5 \text{ V}$, $I_{IN} = 0$ $V_{OUT} = 50 \text{ V}$, $T_a = 85^\circ\text{C}$	—	—	100	μA
Output Saturation Voltage		$V_{CE(sat)}$	2	$V_{CC} = 4.5 \text{ V}$ $V_{IN} = V_{IN(ON)}$ Max. $I_{OUT} = 350 \text{ mA}$	—	1.4	2.0	V
Input Current	Output On	$I_{IN(ON)}$	3	$V_{CC} = 5.5 \text{ V}$, $V_{IN} = 0.4 \text{ V}$	—	-0.32	-0.45	mA
	Output Off	$I_{IN(OFF)}$	4	$V_{CC} = 5.5 \text{ V}$, $V_{IN} = -20 \text{ V}$	—	—	-2.6	
Input Voltage (Output on)		$V_{IN(ON)}$	5		—	—	$V_{CC} - 3.7$	V
Clamp Diode Reverse Current		I_R	6	$V_R = 50 \text{ V}$, $T_a = 25^\circ\text{C}$ (Note 1)	—	—	50	μA
				$V_R = 50 \text{ V}$, $T_a = 85^\circ\text{C}$ (Note 1)	—	—	100	
Clamp Diode Forward Current		V_F	7	$I_F = 350 \text{ mA}$	—	—	2.0	V
				$I_F = 280 \text{ mA}$	—	—	1.8	
Supply Current	$I_{CC(ON)}$		8	$V_{CC} = 5.5 \text{ V}$, $V_{IN} = 0$	—	17	22	mA
	$I_{CC(OFF)}$			$V_{CC} = 5.5 \text{ V}$, $V_{IN} = V_{CC}$	—	—	100	
Turn-On Delay	t_{ON}		9	$V_{CC} = 5 \text{ V}$, $V_{OUT} = 50 \text{ V}$ (Note 1) $R_L = 125 \Omega$, $C_L = 15 \text{ pF}$	—	0.1	—	μs
Turn-Off Delay	t_{OFF}				—	3	—	

TEST CIRCUIT

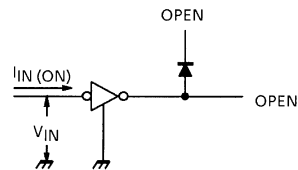
1. I_{CEX}



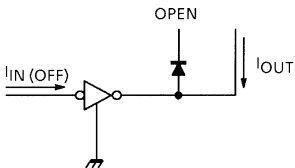
2. $V_{CE(sat)}$



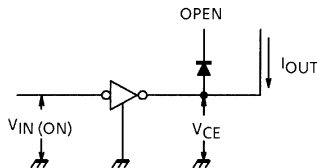
3. $I_{IN(ON)}$



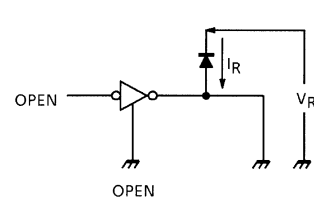
4. $I_{IN(OFF)}$

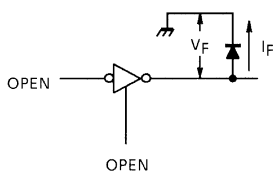
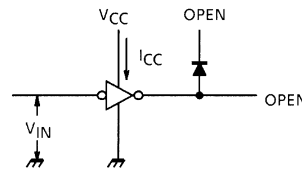
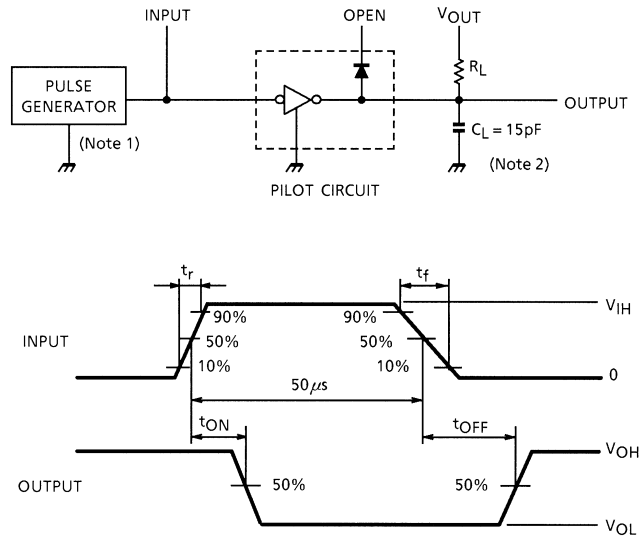


5. $V_{IN(ON)}$



6. I_R

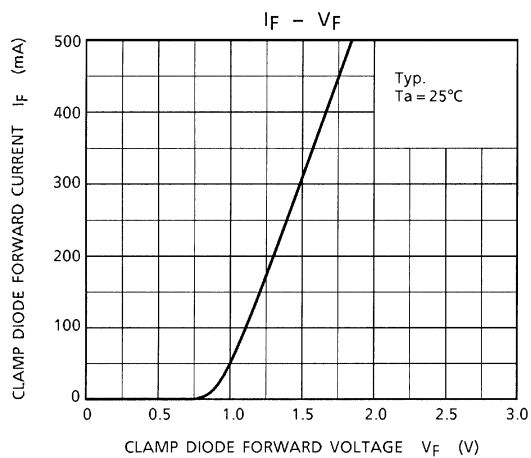
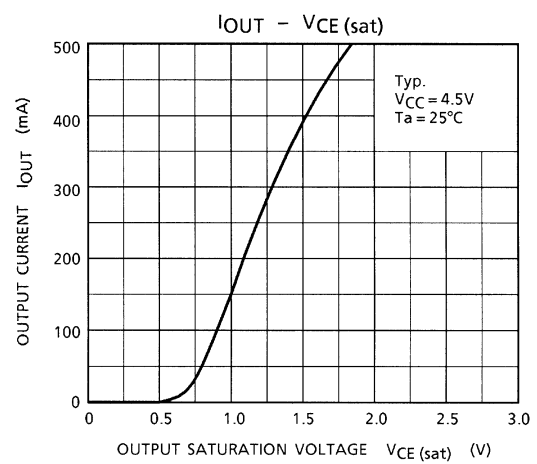
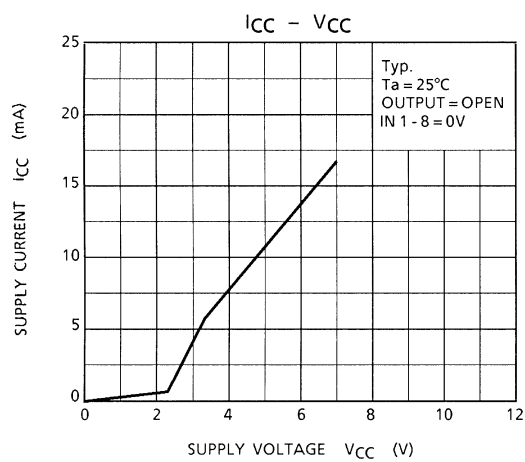
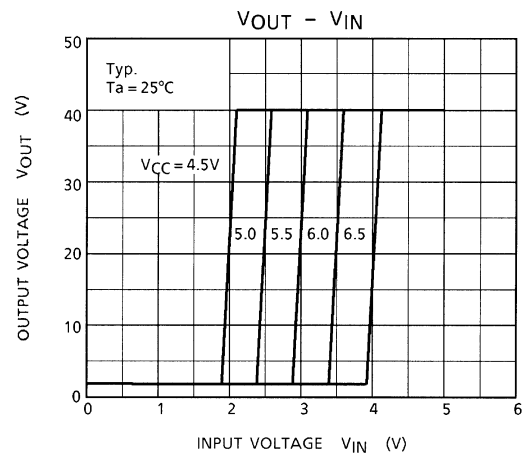
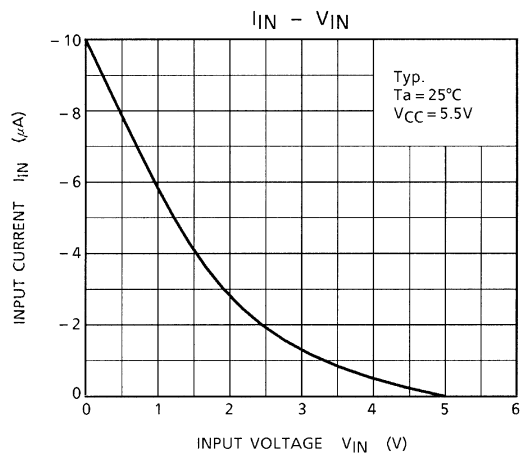


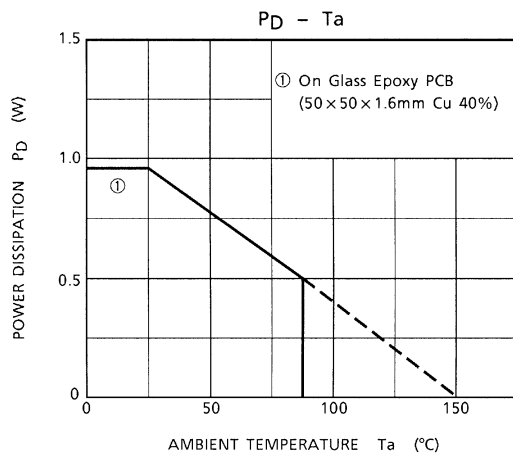
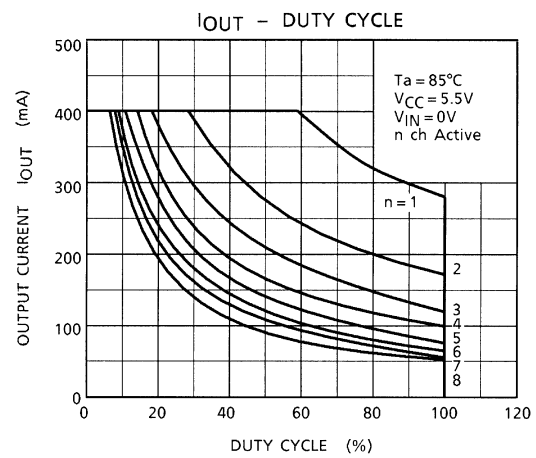
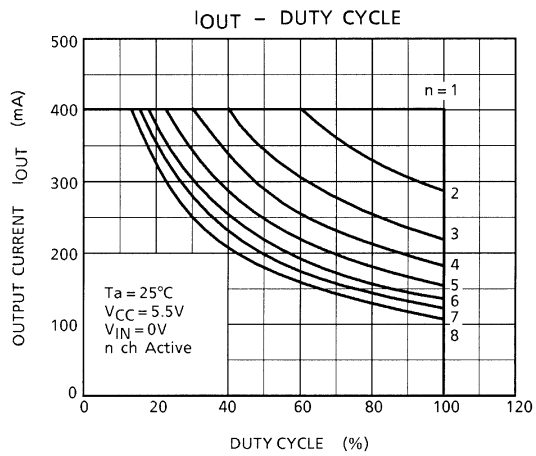
7. V_F

8. I_{CC}

9. t_{ON} , t_{OFF}


Note 1: Pulse Width 50 μ s, Duty Cycle 10%
 Output Impedance 50 Ω , $t_r \leq 5$ ns, $t_f \leq 10$ ns
 Note 2: C_L includes probe and jig capacitance.

PRECAUTIONS for USING

This IC does not integrate protection circuits such as overcurrent and overvoltage protectors. Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC. Utmost care is necessary in the design of the output line, V_{CC} , COMMON and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

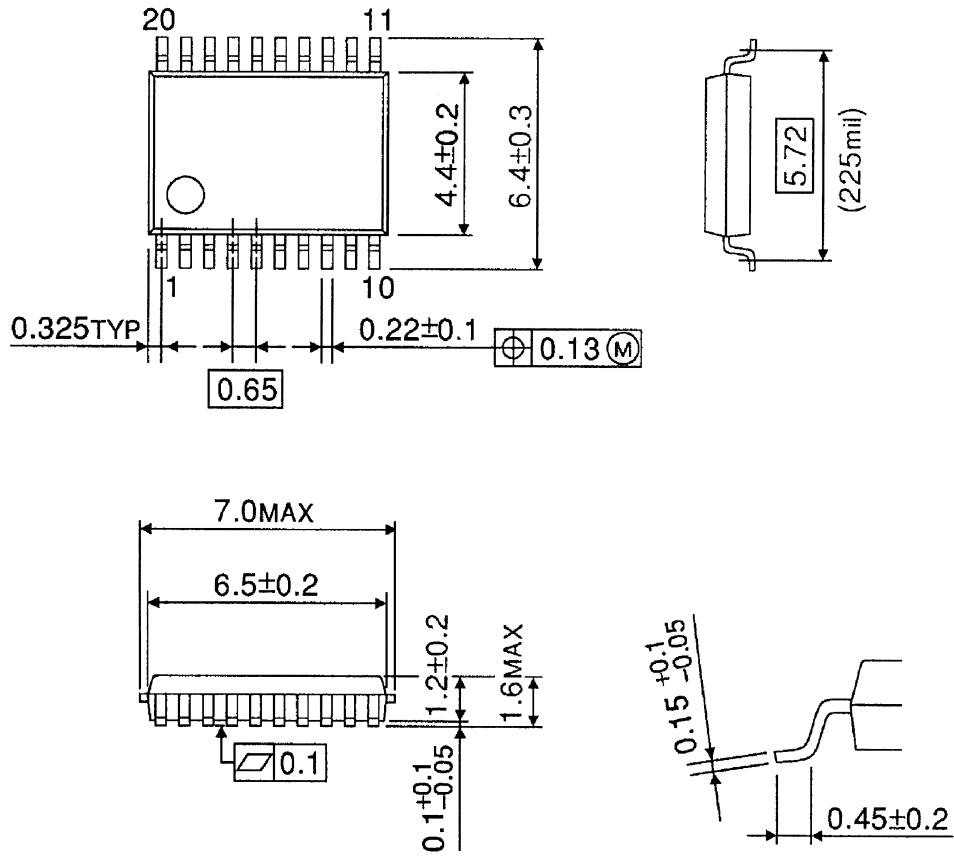




PACKAGE DIMENSIONS

SSOP20-P-225-0.65A

Unit: mm



Weight: 0.09 g (Typ.)

About solderability, following conditions were confirmed

- Solderability

- (1) Use of Sn-63Pb solder Bath

- solder bath temperature = 230°C
 - dipping time = 5 seconds
 - the number of times = once
 - use of R-type flux

- (2) Use of Sn-3.0Ag-0.5Cu solder Bath

- solder bath temperature = 245°C
 - dipping time = 5 seconds
 - the number of times = once
 - use of R-type flux

RESTRICTIONS ON PRODUCT USE

030619EBA

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